

National Institute of Technology Calicut
Department of Physics
Thin Film Technology PH3024
Test 2 Examination, Winter Semester April - 2015

Duration: 1 hour

Max Marks: 20

Answer all questions

(2X5 = 10M)

1. Define vacuum sputtering. Mention any (six) important characteristics of sputtering process.
2. Explain, with a neat diagram, the working principle and applications of Plasma Enhanced CVD?

(5X2 = 10M)

1. Discuss the various types of evaporation sources.
2. Write the advantages of electron beam evaporation over thermal evaporation.
3. Write the two differences between physical vapour deposition (PVD) and chemical vapour deposition (CVD) techniques.
4. Discuss the CVD reaction mechanism?
5. Write any 4 characteristics of UHVCVD?
